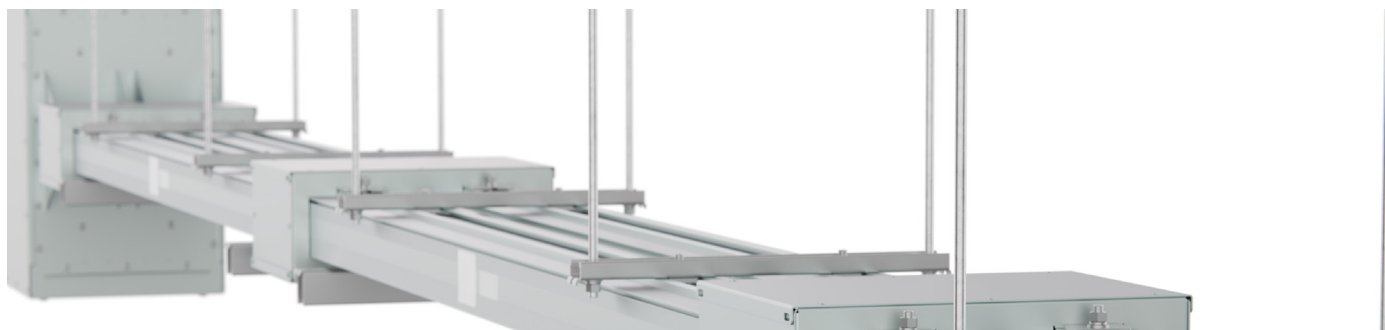




T5 DOUBLEBAR



TECHNICAL ENABLERS

- ✓ **High-density double-bar architecture:** Parallel conductors increase amperage and pluggable space without increasing footprint.
- ✓ **Compact, high-amperage design:** Supports power requirements up to 2000A while delivering busduct-level power density in T5 open-channel form designed for white space.
- ✓ **Low-loss conductor interfaces:** Silver-plated adapter blades reduce resistance and improve thermal performance.
- ✓ **Designed to support HCP deployment:** Accommodates more high capacity plug-ins along the busway without performance tradeoffs.
- ✓ **High stress validated:** Tested for short-circuit and thermal performance.
- ✓ **Modular & scalable:** Modular design supports multiple ratings without system redesign.
- ✓ **T5 ecosystem compatibility:** Maintains open-channel plug-in access & compatibility with all T5 plug-in units.



WHY IT MATTERS

- ✓ **Built for AI rack power densities:** Supports 100 kW+ racks without the need for independent parallel systems.
- ✓ **More power per linear foot:** Maximizes capacity while minimizing infrastructure.
- ✓ **Enables HCP-driven AI rack density:** Supports higher HCP attach rates as AI rack power requirements scale.
- ✓ **Thermal margin for continuous load:** Designed for sustained and cyclic AI workloads.
- ✓ **Faster scaling and future readiness:** Scales with next-generation power demands, including DC power installations up to 1000 VDC.
- ✓ **Differentiated vs. legacy busway:** Higher density with greater modularity and flexibility.

